IN THE CLAIMS

(Previously Presented) A semiconductor laser light emitting device comprising:
a stack of group III nitride semiconductor films;

wherein each group III nitride semiconductor film comprises an element selected from the group consisting of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stack of group III nitride semiconductor films is formed into a ridge-like stripe, to form a current injection region;

wherein a current injection width Wst of said current injection region is at a value in a range of 1 $\mu m \leq Wst \leq 3 \mu m$; and

wherein said current injection region is formed on an active layer;

a current non-injection region formed on both sides of said ridge-like strip current injection region, wherein said current non-injection region comprises a material expressed by a chemical formula $Al_xGa_{1-x}N$, wherein the component ratio "x" of Al is at a value in a range of $0.3 \le x \le 1.0$; and

a film located between the active layer and the current non-injection region, comprising a material expressed by a chemical formula $Al_xGa_{1-x}N$ (0.3 $\leq x \leq$ 1.0), and having a combined thickness of less than or equal to 0.2 μm but greater than zero.

Claims 2-4 (Cancelled)

5. (Original) A semiconductor laser light emitting device according to claim 1, wherein a difference Δn between an effective refractive index n1 of said current injection region

in the film stacking direction and an effective refractive index n2 of said current non-injection region in the film stacking direction is in a range of $0.007 \le \Delta n = (n1-n2) \le 0.012$.

Claims 6-8 (Cancelled)

9. (Previously Presented) A semiconductor laser light emitting device comprising: a stack of group III nitride semiconductor films;

wherein each group III nitride semiconductor film comprises an element selected from the group consisting of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stack of group III nitride semiconductor films comprises is formed into a ridge-like stripe, to form a current injection region;

wherein a current injection width Wst of said current injection region is at a value in a range of 1 μ m \leq Wst \leq 3 μ m; and

wherein said current injection region is formed on an active layer;

a current non-injection region formed on both sides of said ridge-like strip current injection region, wherein said current non-injection region comprises a material expressed by a chemical formula $Al_xGa_{1-x}N$, wherein the component ratio "x" of Al is at a value in a range of 0.15 < x < 0.30; and

wherein the group III nitride semiconductor films located between the active layer and the current non-injection region, comprises a material expressed by a chemical formula Al_xGa_{1-} xN (0.15 $\leq x \leq$ 0.30), and have a combined thickness of less than or equal to 0.2 μ m but greater than zero.

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Claims 10-12 (Cancelled)

13. (Original) A semiconductor laser light emitting device according to claim 9, wherein a difference Δn between an effective refractive index n1 of said current injection region in the film stacking direction and an effective refractive index n2 of said current non-injection region in the film stacking direction is in a range of $0 < \Delta n = (n1-n2) < 0.007$.

Claims 14-29 (Cancelled)

30. (Previously Presented) A semiconductor laser light emitting device comprising: a stack of group III nitride semiconductor films;

wherein each group III nitride semiconductor film comprises an element selected from the group consisting of aluminum, gallium, indium, and boron;

wherein, an upper portion of said stack of group III nitride semiconductor films forms a ridge-like stripe for a current injection region;

wherein a current non-injection region formed on both sides of said ridge-like strip current injection region, wherein said current non-injection region comprises a material expressed by a chemical formula $Al_xGa_{1-x}N$; and

a film located between an active layer and the current non-injection region, comprising a material expressed by a chemical formula $Al_xGa_{1-x}N$ (0.15 $\leq x \leq$ 0.30), and having a combined thickness of less than or equal to 0.2 μ m but greater than zero.